

EconoPIM2 SixPack IGBT Module

$V_{CES}=1200V$, $I_C=75A$, $V_{CE(sat)}=1.9V$

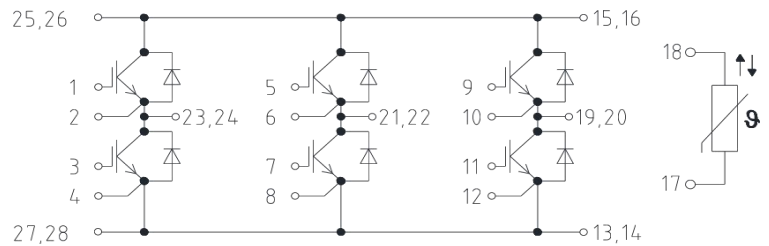
Features

- IGBT Inverter Short Circuit Rated 10 μ s
- $V_{CE(sat)}$ With Positive Temperature Coefficient
- 100% RBSOA Tested
- HI-REL Power Terminals



Applications

- Inverters
- Servo Drives
- UPS Systems



IGBT, Inverter Maximum Ratings

Parameter	Symbol	Condition	Value	Unit
Collector-emitter voltage	V_{CES}		1200	V
Gate-emitter peak voltage	V_{GES}		± 20	V
Continuous DC collector current	$I_{C\ nom}$	$T_C=80^\circ C$	75	A
		$T_C=25^\circ C$	150	A
Repetitive peak collector current	I_{CRM}	$T_{vj}=150^\circ C$	150	A
Short circuit withstand time	t_{sc}	$T_{vj}=125^\circ C$	>10	us
Maximum power dissipation(IGBT)	P_D	$T_C=25^\circ C$, $T_{vj}=150^\circ C$	450	W

Characteristics Values

Parameter	Symbol	Conditions	Value			Unit	
			Min.	Typ.	Max.		
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=50A$, $V_{GE}=15V$	$T_{vj}=25^\circ C$	1.9	2.1	V	
			$T_{vj}=125^\circ C$	2.2		V	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=1mA$, $V_{CE}=V_{GE}$	$T_{vj}=25^\circ C$	4.5	5.4	6.5	V
Gate charge	Q_G	$I_C=75A$, $V_{CE}=600V$, $V_{GE}=-15V...+15V$		0.63		μC	
Input capacitance	C_{ies}	$f=1MHz$, $V_{CE}=25V$, $V_{GE}=0V$	$T_{vj}=25^\circ C$	10.4		nF	
Output capacitance	C_{oes}	$f=1MHz$, $V_{CE}=25V$, $V_{GE}=0V$	$T_{vj}=25^\circ C$	0.56		nF	
Collector-emitter cut-off current	I_{CES}	$V_{CE}=V_{CES}$, $V_{GE}=0V$	$T_{vj}=25^\circ C$		500	μA	
			$T_{vj}=125^\circ C$		1	mA	

Gate-emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=V_{GES}$	$T_{vj}=25^{\circ}C$		300	nA
			$T_{vj}=125^{\circ}C$		600	nA
Turn-on delay time	$t_{d\ on}$	$I_C=75A, V_{CE}=600V,$ $V_{GE}=-15V/+15V, R_G=15\Omega,$ Inductive Load	$T_{vj}=25^{\circ}C$	190		ns
			$T_{vj}=125^{\circ}C$	175		ns
Rise time	t_r		$T_{vj}=25^{\circ}C$	100		ns
			$T_{vj}=125^{\circ}C$	110		ns
Turn-off delay time	$t_{d\ off}$		$T_{vj}=25^{\circ}C$	270		ns
			$T_{vj}=125^{\circ}C$	280		ns
Fall time	t_f		$T_{vj}=25^{\circ}C$	160		ns
			$T_{vj}=125^{\circ}C$	240		ns
Turn-on switching loss	E_{on}		$T_{vj}=25^{\circ}C$	5.2		mJ
			$T_{vj}=125^{\circ}C$	6.9		mJ
Turn-off switching loss	E_{off}	$T_{vj}=25^{\circ}C$	3.6		mJ	
		$T_{vj}=125^{\circ}C$	5.5		mJ	
Total switching loss	E_{ts}	$T_{vj}=25^{\circ}C$	8.8		mJ	
		$T_{vj}=125^{\circ}C$	12.4		mJ	
Reverse bias safe operating area	RBSOA	$I_C=150A, V_{CC}=960V,$ $V_p=1200V, R_g=15\Omega,$ $V_{GE}=+15V\ to\ 0V,$	$T_{vj}=150^{\circ}C$	Trapezoid		
Short circuit safe operating area	SCSOA	$V_{GE}=15V, V_{CE}=600V$	$T_{vj}=150^{\circ}C$	10		us

Diode, Inverter Maximum Ratings

Parameter	Symbol	Conditions	Value	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj}=25^{\circ}C$	1200	V
Continuous forward current	I_F		75	A
Repetitive peak forward current	I_{FRM}	$t_p=1ms$	100	A
I^2t -value	I^2t	$t_p=10ms, V_R=0V$	$T_{vj}=125^{\circ}C$ 1200	A^2s

Characteristics Values

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Forward voltage	V_F	$I_F=75A, V_{GE}=0V$	$T_{vj}=25^{\circ}C$	2.0	2.2	V
			$T_{vj}=125^{\circ}C$	2.2		V
Reverse recovery time	t_{rr}	$I_F=75A,$ $V_R=600V,$ $V_{GE}=-15V,$ $di/dt=750A/\mu s$	$T_{vj}=25^{\circ}C$	190		ns
			$T_{vj}=125^{\circ}C$	200		ns
Peak reverse recovery current	I_{rr}		$T_{vj}=25^{\circ}C$	46		A
			$T_{vj}=125^{\circ}C$	75		A
Recovered charge	Q_{rr}		$T_{vj}=25^{\circ}C$	4.5		μC
			$T_{vj}=125^{\circ}C$	9.1		μC
Reverse recovery energy	E_{rec}		$T_{vj}=25^{\circ}C$	1.2		mJ
			$T_{vj}=125^{\circ}C$	3.2		mJ

NTC-Thermistor
Characteristics Values

Symbol	Condition	Typ.	Max.	Unit
R ₂₅	T _C =25°C	5		kΩ
ΔR/R	T _C =100°C , R ₁₀₀ =481Ω		±5	%
P ₂₅	T _C =25°C	50		mW
B _{25/50}	R ₂ =R ₂₅ exp[B _{25/50} (1/T ₂ -1/(298.15K))]	3380		K
B _{25/80}	R ₂ =R ₂₅ exp[B _{25/80} (1/T ₂ -1/(298.15K))]	3440		K

Module
Characteristics Values

Parameter	Symbol	Conditions	Value	Unit
Isolation test voltage	V _{ISOL}	f=50Hz, t=1min	2.5	kV
Operating junction temperature of IGBT	T _{vj}	Inverter& Brake& Rectifier	-40~+175	°C
Operating junction temperature of diode	T _{vj}	Inverter& Brake& Rectifier	-40~+155	°C
Storage temperature	T _{stg}		-40~+125	°C

Thermal Characteristics

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Inverter	R _{θJC}	Junction-To-Case (IGBT Part, Per Leg)			0.33	°C/W
	R _{θJC}	Junction-To-Case (Diode Part, Per Leg)			0.39	°C/W
Module	R _{θJC}	Case-To-Sink (conductive grease applied)			0.1	°C/W
	M	Mounting torque for module mounting:M6		4	6	N·m
	G	Weight			180	g

Notes:

(1) Repetitive Rating: Pulse width limited by max. junction temperature

Typical Characteristics

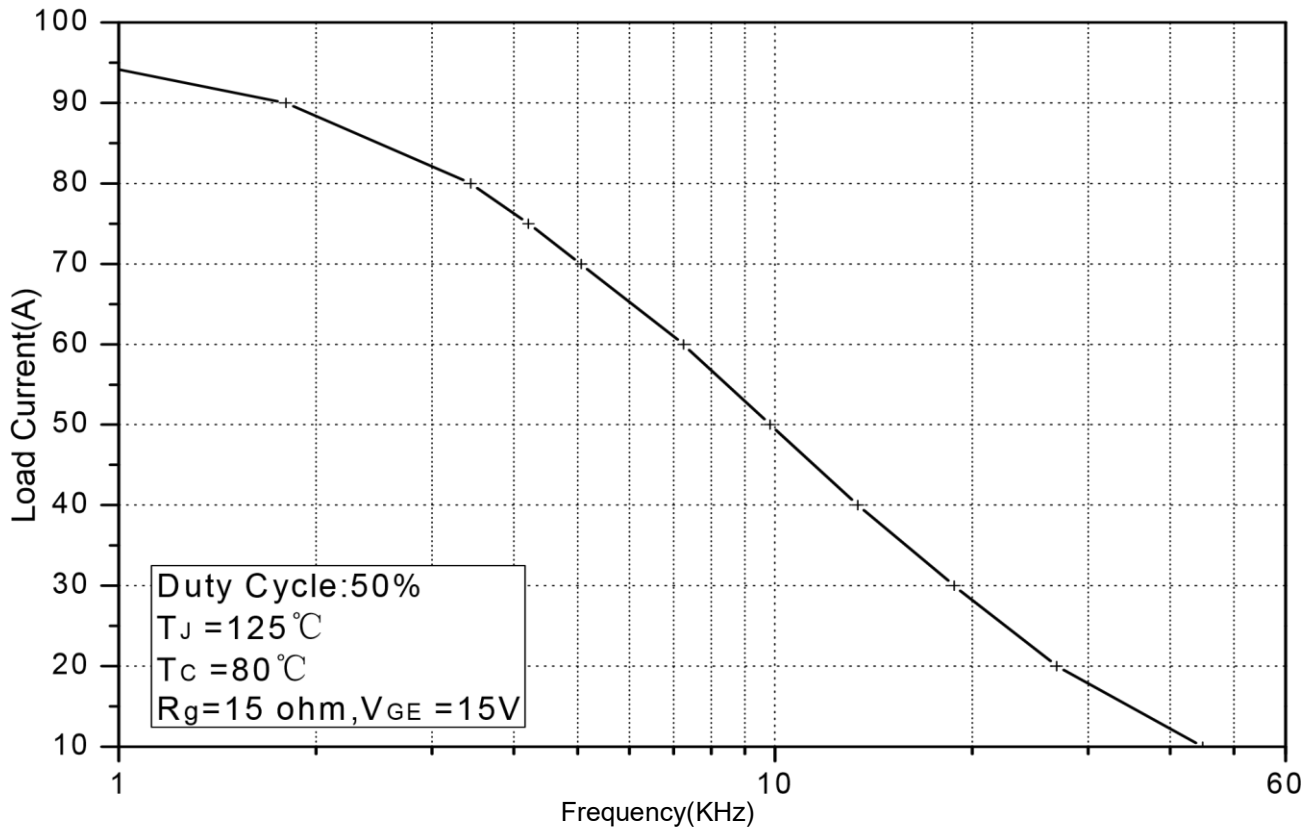


Fig.1 Typical Load Current vs. Frequency (IGBT Inverter)

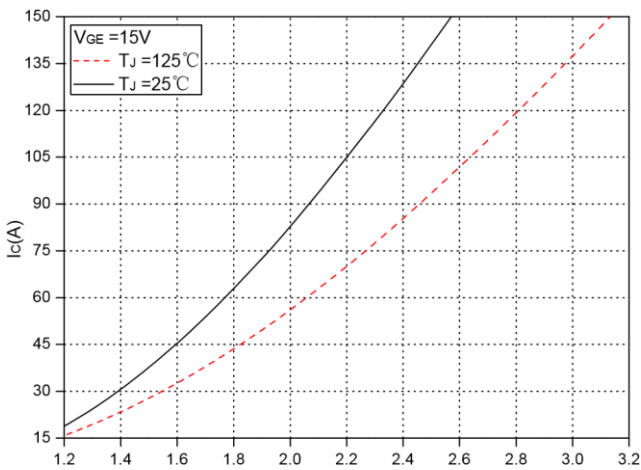


Fig.2 Typical Saturation Voltage Characteristics $T_{vj}=25^\circ\text{C}$, (IGBT Inverter)

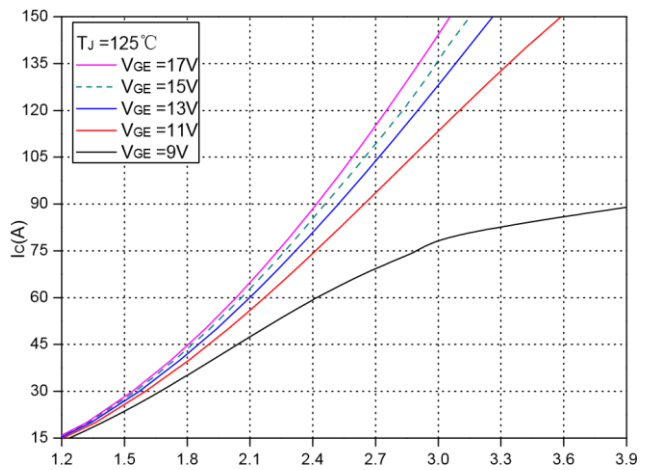


Fig.3 Typical Collector Current vs. Gate Resistance $V_{GE}=\pm 15\text{V}$, $R_{Gon}=R_{Goff}=22\Omega$, $V_{CE}=600\text{V}$ (IGBT Inverter)

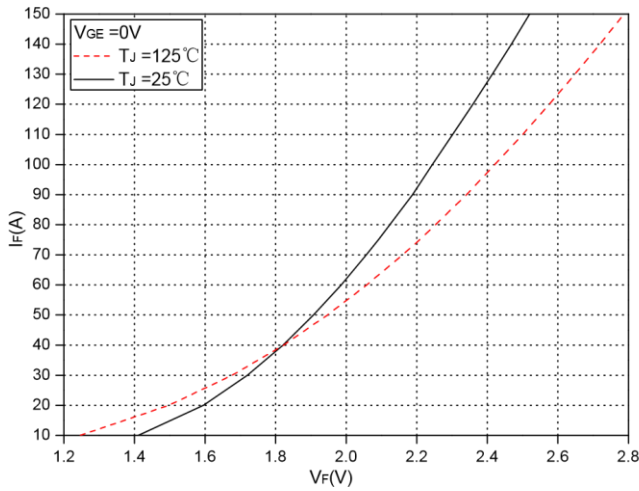


Fig.4 Forward Characteristics of FWD (Diode Inverter)

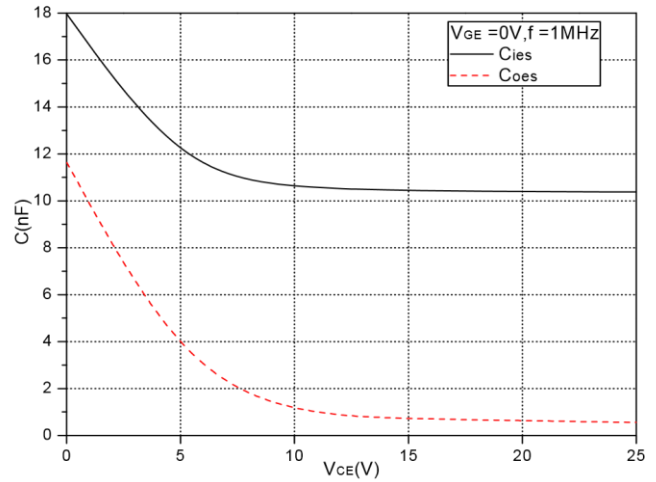


Fig.5 Capacitance Characteristics (IGBT Inverter)

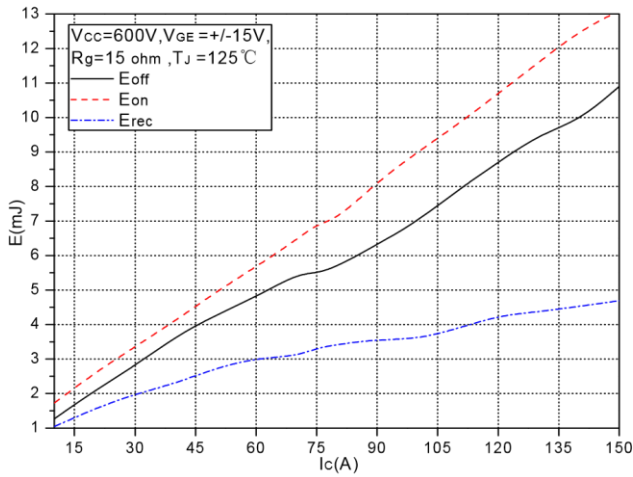


Fig.6 Typical Switching Loss vs. Collector Current (IGBT & Diode Inverter)

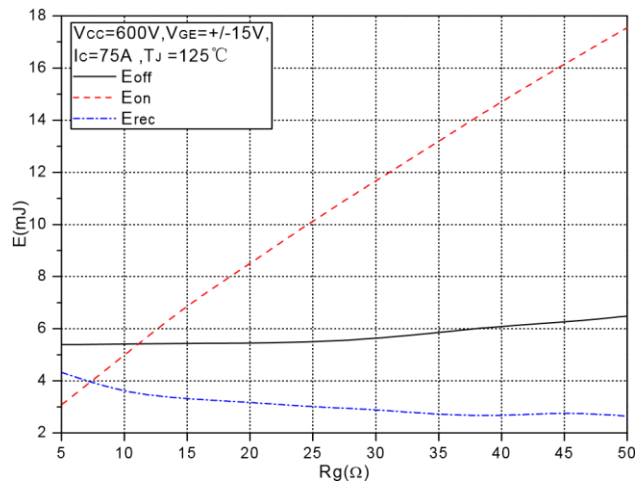


Fig.7 Typical Switching Loss vs. Gate Resistance (IGBT & Diode Inverter)

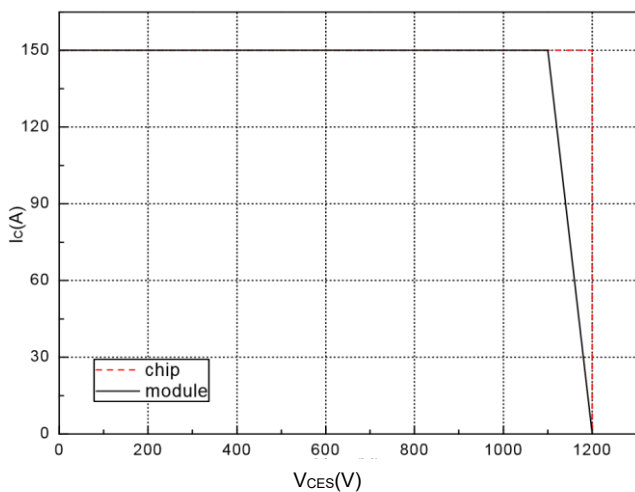


Fig.8 Reverse Bias Safe Operation Area (RBSOA) (IGBT Inverter)

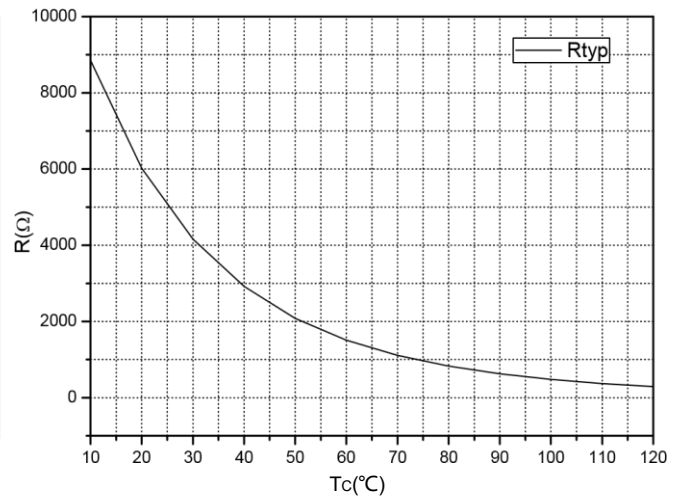


Fig.9 NTC Temperature characteristics

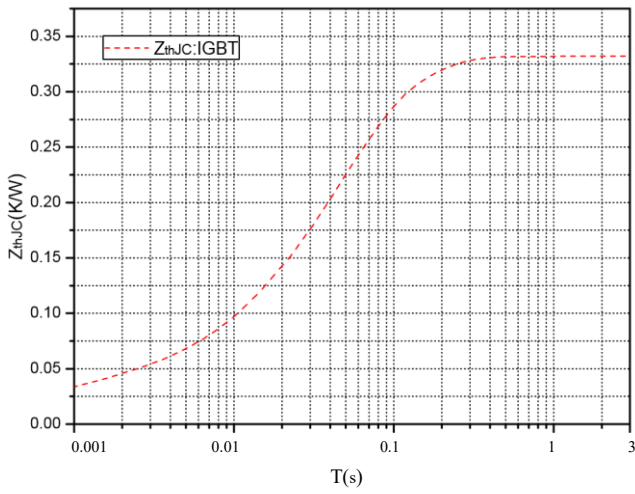


Fig.10 Transient thermal impedance (IGBT Inverter)

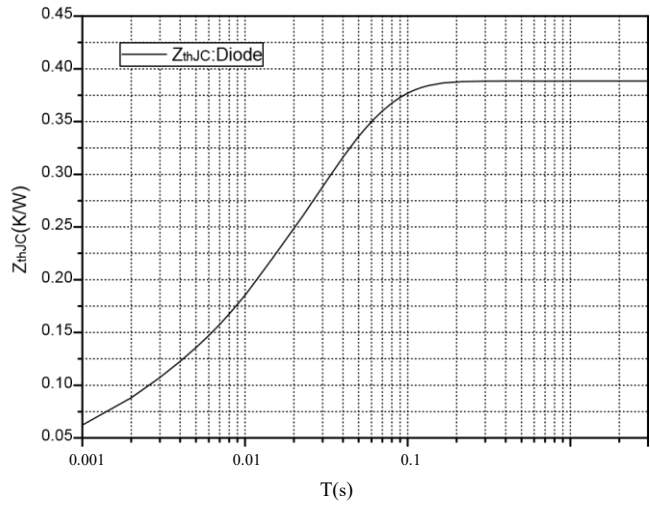
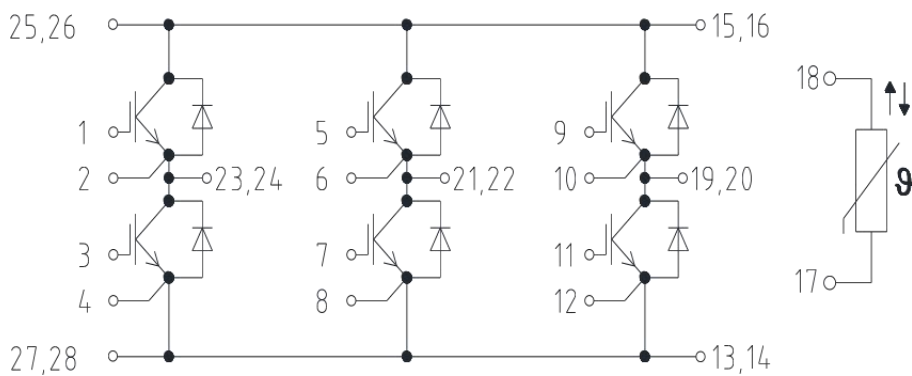
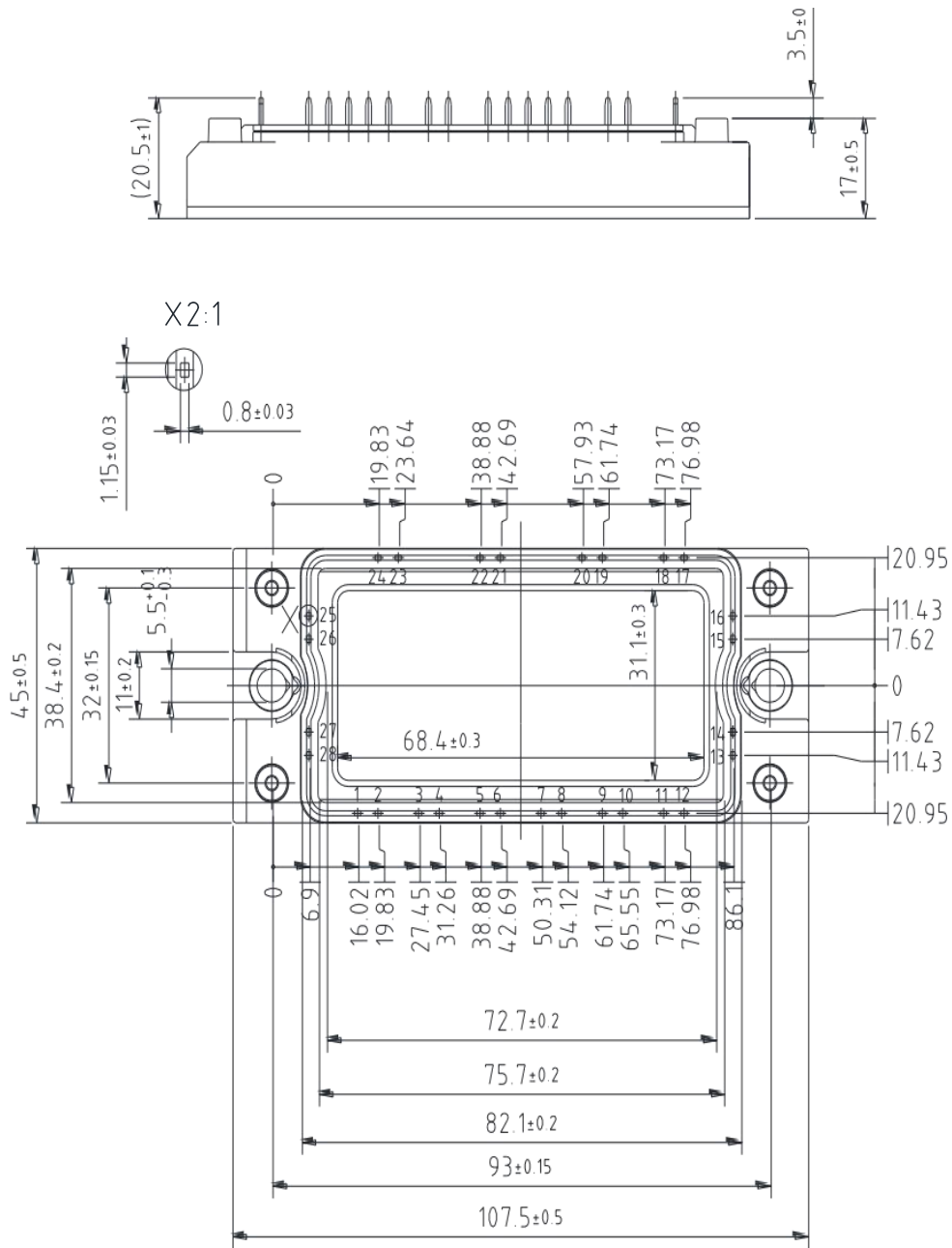


Fig.11 Transient thermal impedance (Diode Inverter)

Circuit Diagram



Package Outlines (Unit:mm)



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